L Number	Hits	Search Text	DB	Time stamp
11	176	333/33,34,247,260.ccls. and (MMW or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:33
12	176	333/33,34,247,260.ccls. and (MMW or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:34
13	48	(SMA near connector$1) and (thermal near expansion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:35
14	103	257/$.ccls. and mmic and (thermal with coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:36
16	19	257/691,728,699.ccls. and monolithic and microstrip and (thermal with coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:38
17	22	333/33,34,247,246,260.ccls. and MMIC and (thermal with coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:39
18	218	333/33,34,247,246,260.ccls. and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:40
22	45	thermal and housing and MMW	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 10:00
23	4	monolithic and (stress$3 with relief with portions) and (heat or thermal) and pedestal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 10:51
-	2620	333/33,34,247,260.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 19:03
-	132	333/33,34,247,260.ccls. and (MMW or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/24 09:33
-	10	((hous$3 or enclos$4) with transceiver$1) and (MMW or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 09:13
-	0	333/33,34,247,260.ccls. and (MMW with module$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 19:00
-	0	333/33,34,247,260.ccls. and (MMW same module$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 19:00